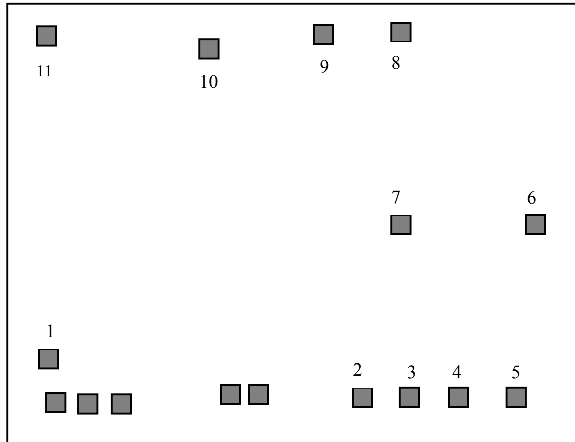
Supertex inc.

HV831-6in
Die Specifications



Pad Coordinates in Microns:

1	000.0	;	000.0
2	962.5	;	-174.0
3	1122.5	;	-174.0
4	1282.5	;	-174.0
5	1442.5	;	-174.0
6	1482.0	;	433.5
7	1074.0	;	433.5
8	1060.5	;	892.5
9	900.5	;	888.5
10	611.0	;	837.0
11	-0.5	;	896.5

HV831-6in

Pad	Function
1	C_1
2	V_{DD}
3	Rsw-osc
4	C_2
5	GND
6	GND
7	L_X
8	Cs
9	Com
10	EL_2
11	EL_1

Die Specifications

	mils	mm		
Die Size:	69.3 x 57.9	1.76 x 1.47	Back Side Metal:	None
Die Thickness:	11	0.28	Back Side Potential:	GND
Bond Pad Size:	4 x 4	0.10 x 0.10	Die Attach Material:	Epoxy
Bond Wire Size:	1.25 - 1.3	0.032 - 0.033	Bond Pad Metal:	Al/Si/Cu